

**IN THE SPECIFICATION:**

Please amend the paragraph on page 2, beginning at line 5, as follows:

Urethane, metal or the like is used as the material for the printing squeegee 4. [[Since]]  
Because the squeegee of urethane, if used, has the problem that the urethane is scraped off by an  
edge portion of the metal mask to leave fragments on the board or solder paste pattern, [[the]] a  
squeegee of metal is generally used.

Please amend the paragraph beginning on page 5, beginning at line 18, as follows:

However, if electronic devices and circuit boards having parts mounted thereon are  
discarded in the natural environment after use without being suitably disposed of, there arises the  
problem that lead, which is toxic heavy metal, will flow out in the form of soluble compounds by  
being exposed to acid rain, not only adversely affecting the global environment but also exerting  
influence on animals, plants and human bodies by ingressing into underground water or other  
water systems. For this reason, it is strongly ~~required~~ desireable to use lead-free solders.

Please amend the paragraph on page 4, beginning at line 2, as follows:

In the case where such a tin-silver, tin-silver-copper or like lead-free solder paste of high  
melting point is to be printed on circuit boards, the lead-free solder paste is filled into rectangular  
openings 11 formed in a metal mask 1 as shown in FIG. 3, and a printing squeegee 4 of metal is  
thereafter moved along the metal mask 1 as shown in FIG. 7(a). If the openings 11 are each so

large as to exceed 5 mm.<sup>sup.2</sup> in area, great frictional heat is liable to occur between the printing metal squeegee 4 and edge portions 15 of the opening 11 in the metal mask 1 shown in FIG. 7(b). Further because the opening 11 is rectangular in shape, the lead-free solder paste filled in is low in fluidity and is liable to be heated to a high temperature, especially at the edge portion 15. However, the flux incorporated in the lead-free solder paste has characteristics to undergo a chemical change and deteriorate (oxidize) when exposed to a high temperature, so that the flux markedly deteriorates (oxidizes) ~~owing to~~ as a result of the frictional heat to result in impaired solder wettability. This seriously lowers the bond strength between a lead member or like large part and the circuit board, entailing the problem that the part becomes removed from the circuit board when subjected, for example, to external pressure or stress.